

CP705V PNP - High Current Transistor Die 1.0 Amp, 80 Volt

The CP705V is a silicon PNP transistor designed for high current, general purpose amplifier applications.

		MECHANICA	AL SPECIFICAT	IONS:	
		Die Size		31 x 31 MILS	
		Die Thicknes	SS	7.1 MILS	
		Base Bondir	ng Pad Area	5.9 x 11.8 MILS	
		Emitter Bond	ding Pad Area	6.5 x 13.8 MILS	
		Top Side Metalization		AI – 30,000Å	
		Back Side Metalization		Au – 9,000Å	
		Scribe Alley Width		1.96 MILS	
		Wafer Diameter		5 INCHES	
		Gross Die Per Wafer		17,534	
MAXIMUM RATINGS: $(T_A=25^{\circ}C)$ SYMBOL UNITS					
Collector-Base Voltage			V _{CBO}	80	V
Collector-Emitter Voltage			VCEO	80	V
Emitter-Base Voltage			V _{EBO}	5.0	V
Continuous Collector Current			ΙC	1.0	А
Operating and Storage Junction Temperature			T _{J,} T _{stg}	-65 to +150	°C
	L CHARACTERISTIC	S: (T₄=25°C	unless otherwise	noted)	
SYMBOL ICBO	TEST CONDITIONS		MIN	MAX 500	UNITS nA
IEBO	V _{EB} =5.0V			500	nA
BV _{CBO}	Ι _C =10μΑ		80		V
BVCEO	I _C =10mA		80		V
BVEBO	Ι _Ε =10μΑ		5.0		V
V _{CE(SAT)}	I _C =500mA, I _B =50m	A		0.50	V
V _{BE(SAT)}	I _C =500mA, I _B =50m	A		1.10	V
h _{FE}	V _{CE} =5.0V, I _C =100	mA	100	700	
fT	V _{CE} =10V, I _C =50m/	A, f=1.0MHz	100		MHz
Cob	V _{CB} =10V, I _E =0, f=	1.0MHz		20	pF
C _{ib}	V _{EB} =0.5V, I _C =0, f=	1.0MHz		110	pF

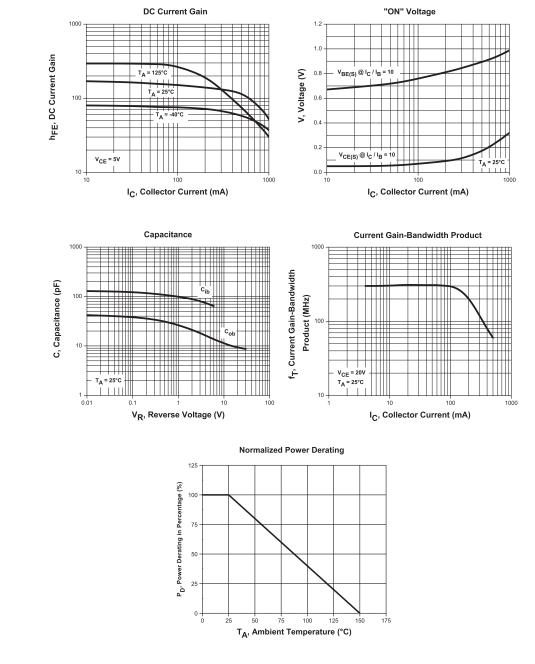
MECHANICAL SPECIFICATIONS:

R5 (10-October 2013)

CP705V Typical Electrical Characteristics



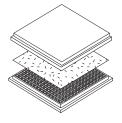
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BARE DIE PACKING OPTIONS



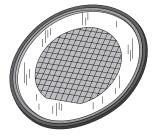


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- · Environmental regulation compliance
- Customer specific screening
- · Up-screening capabilities

· Custom product packing

Custom bar coding for shipments

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when 1. ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA Main Tel: (631) 435-1110 Main Fax: (631) 435-1824 Support Team Fax: (631) 435-3388 www.centralsemi.com

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